



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-13
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TSX632IQ2T	AYXP*UY28AAA	A	Z6HA	2017-06-13
Amount		UoM	Unit type	ST ECOPACK Grade
8.07		mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2X2X0.75	8	No lead	
Comment	XP MLPD/DFN 2x2x0.75 8L PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AYXP*UY28AAA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.843	mg		Silicon Die	Si	7440-21-3		0.796	mg	944247	98637
Silicon Die					metallization	Tungsten (W)	7440-33-7		0.001	mg	1186	124
Silicon Die					passivation	Silicon Nitride (SiN)	68034-42-4		0.005	mg	5931	620
Silicon Die					passivation	Silicon Oxide(SiO2)	7631-86-9		0.025	mg	29656	3098
Silicon Die					passivation	PIX1 Gamma-butyrolactone	96-48-0		0.016	mg	18980	1983
Leadframe	Copper & its alloys	1.6708	mg		Alloy	Copper	7440-50-8		1.646	mg	985157	203965
Leadframe					Alloy	Nickel	7440-02-0		0.019	mg	11372	2354
Leadframe					Alloy	Iron	7439-89-6		0.001	mg	599	124
Leadframe					Alloy	Zinc	7440-66-6		0.002	mg	1197	248
Leadframe					Alloy	Iron Phosphide(FeP)	26508-33-8		0.0005	mg	299	62
Leadframe					Alloy	Palladium	7440-05-3		0.002	mg	1197	248
Leadframe					Alloy	Gold	7440-57-5		0.0003	mg	180	37
Die Attach	Other Organic Materials	0.085	mg		Epoxy	Aluminium oxide	1344-28-1		0.026	mg	305882	3222
Die Attach					Epoxy	Diethylene glycol monoethyl ether acetate	112-15-2		0.034	mg	400000	4213
Die Attach					Epoxy	Epoxy resin	25068-38-6		0.006	mg	70588	743
Die Attach					Epoxy	Epoxy resin	Proprietary		0.017	mg	200000	2107
Die Attach					Epoxy	Aromatic amine	Proprietary		0.002	mg	23529	248
Bonding wire	Precious metals	0.034	mg		Bonding wire	Au	7440-57-5		0.034	mg	1000000	4213
Encapsulation	Other Organic Materials	5.437	mg		Molding compound	Silica Fused	60676-86-0		5.095	mg	937098	631351
Encapsulation					Molding compound	Epoxy Resin	25068-38-6		0.163	mg	29980	20198
Encapsulation					Molding compound	Phenol Resin	29690-82-2		0.163	mg	29980	20198
Encapsulation					Molding compound	Carbon Black	1333-86-4		0.016	mg	2943	1983